

ECE 482

Fall 2026

Review Notes for ECE 482 (Digital IC Design)

These notes aren't fully comprehensive.

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Contents

1	Intro & MOSFET Static Analysis	1
2	Dynamic Analysis of CMOS Inverter	4
2.1	MOS Capacitances	4
2.1.1	PN-junction Capacitances	5

1 Intro & MOSFET Static Analysis

- By the textbook convention, we have a positive drain current when it flows into the drain.
 - NMOS drain current should be positive, PMOS should be negative.
- Industry is going towards SiP instead of SoC because of yield issues and reticle sizes making large monolithic dies unlikely

Technology Scaling

- generation is 18 – 24 months
- feature sizes shrink $\sim 0.7x$ per generation, $2x$ transistors per area (insert Dennard Scaling mention here)
- STI (the other one) stands for shallow trench isolation and can prevent leakage between adjacent transistors
- Moore's Law

Supply Voltage Scaling

- if V_{DD} , L_{gate} , T_{ox} reduce by an identical factor, the lateral and vertical electric fields stay the same, so performance also stays the same.
- power is reduced as well
- historically, L_{gate} was shrunk more aggressively than supply voltage, so transistor feature size scaling virtually stopped at 90nm

Noise

- one of the quality metrics of a digital IC
- can impact the robustness/functionality of a digital IC
 - inductive coupling
 - capacitive coupling
 - power and ground noise
- VTC - Voltage-Transfer Characteristics
 - plot of output voltage as a function of input voltage

Important Parts of a VTC Curve (For an Inverter)

- V_{OL} - output low
- V_{OH} - output high
- V_{IL} - input low (point where derivative of VTC is -1 for the first time)
- V_{IH} - input high (point where derivative of VTC is -1 for the second time)
- V_M - inverter switching threshold (point where $V_{out}(V_{in}) = V_{in}$)
- V_{OL} and V_{OH} are defined wrt. each other.

- In the case of the inverter, we can create a flip-flop by hooking the inputs/outputs of two inverters together.
 - there are two stable operating points $((V_{OH}, V_{OL})$ and $(V_{OL}, V_{OH}))$, and a metastable point

Delay

- t_p - propagation delay from when $V_{in} = V_{50}$ until $V_{out} = V_{50}$
 - $V_{50} = \frac{V_{OH} + V_{OL}}{2}$
- $t_{pLH} \neq t_{pHL}$ necessarily
- One of the ways we can measure delay is through a **ring oscillator**
 - odd number of inverters connected in a circular chain
 - period T of the oscillation is given by $T = 2t_p N$ where N is the number of inverters

Long-Channel Model

When $V_{gs,n} < V_{T,n}$ or $V_{gs,p} > V_{T,p}$, $I_{ds} = 0$

When $V_{ds,n} < V_{dsat,n}$ or $V_{ds,p} > V_{dsat,p}$, $I_{ds} = \mu C_{ox} \left(\frac{W}{L}\right) (V_{ov} V_{ds} - \frac{1}{2} V_{ds}^2)$

When $V_{ds,n} \geq V_{dsat,n}$ or $V_{ds,p} \leq V_{dsat,p}$, $I_{ds} = \frac{1}{2} \mu C_{ox} \left(\frac{W}{L}\right) (V_{ov}^2)$

Instead of using μC_{ox} , we use k'

- under our convention, PMOS k' should be negative

Threshold Voltage

$$V_t = V_{t0} + \gamma \left(\left| \sqrt{V_{sb} - 2\varphi_F} \right| - \sqrt{|-2\varphi_F|} \right)$$

- By design $V_{sb} \geq 0$ for NMOS and $V_{sb} \leq 0$ for PMOS

Short vs. Long Channel

- short channel enters saturation “earlier” at a lower V_{ds}
- in the saturation region, the slope of the short channel device is higher
- no apparent quadratic relation with V_{gs} in saturation region.

Velocity Saturation

- carrier velocity increases linearly with E-field only up to a few kV/cm
- there are a few equations for this, the basic idea being that we define two regions where $E_{lat} < E_c$, and then $E_{lat} = E_c$ where E_c is the critical E-field.

Non-Ideal Effects

- channel-length modulation & DIBL, to account for these, we add V_{ds} related terms to the IV equation.
- $u_{eff} = f(V_{gs})$, in other words, $T_{ox, eff} \neq T_{ox, physical}$

To account for these short-comings of the Long-Channel Model, we introduce the **Short-Channel Model**.

- $I_{ds} = k((V_{gs} - V_t)V_{min} - \frac{1}{2}V_{min}^2)(1 + \lambda V_{ds})$
- $V_{min,n} = \min(V_{ds}, V_{gt}, V_{dsat,n})$ or $V_{min,p} = -\min(|V_{ds}|, |V_{gt}|, |V_{dsat,p}|)$
- high V_t transistor is often called “low power” because leakage current is very low.
- low V_t transistor is often called “high performance” because ON state current will be higher.

Subthreshold Operation

- exponential dependence of I_{ds} on V_{gs} in the subthreshold region.
- neither long or short channels accurately represent I_{ds} in the subthreshold region.
- subthreshold V_t is defined as the V_{gs} at which point $I_d = 100 \text{ [nA]} * (\frac{W}{L})$
 - IV plot is linear below this point, assuming you’re using a semi-log plot.
 - $I_{d, \text{threshold}} = 100(\frac{W}{L})10^{\frac{V_{gs}-V_t}{S}} \text{ [nA]}$
- **there is a parasitic BJT within a MOSFET**, which is where the exponential relation with V_{gs} comes from.

2 Dynamic Analysis of CMOS Inverter

- If we have a square wave input, on the rising edge of the input:
 - our $V_{ds, n} = V_{dd}$
- After t_{pHL} , $V_{ds} = \frac{V_{dd}}{2}$
- Doing KCL on the output node, we get the following equation

$$C_L \frac{dV_{out}}{dt} = k_{n'} \left(\frac{W}{L} \right) \left[(V_{dd} - V_{tn0}) V_{dsatn} - \frac{1}{2} V_{dsatn}^2 \right] (1 + \lambda_n V_{out})$$

$$\int_{V_{dd}}^{\frac{V_{dd}}{2}} \frac{C_L}{I_{dn}} dV_{out} = \int_0^{t_{pHL}} dt = t_{pHL}$$

assuming $(1 + \lambda_n V_{out}) \approx 1$ (1)

$$I_{dn} \approx \left(\frac{W}{L} \right) k_{n'}(\dots) = \left(\frac{W}{L} \right) I_{dsat, n}$$

$$t_{pHL} = \frac{LC_L}{WI_{satn}} \int_{V_{dd}}^{\frac{V_{dd}}{2}} dV_{out} = \frac{LC_L V_{dd}}{2WI_{satn}}$$

Ultimately, we have a similar process when calculating t_{pLH} –the NMOS is in cutoff and the PMOS is in triode/saturation. Thus, we end up with

$$t_{pLH} = \frac{LC_L V_{dd}}{2WI_{satp}} \quad (2)$$

Using an RC model of delay, we end up with

$$t_{pHL} = \frac{0.69}{S} R_{n0} C_L$$

$$t_{pLH} = \frac{0.69}{S\beta} R_{p0} C_L \quad (3)$$

where $S = \frac{W_N}{W_{min}}$ and $\beta = \frac{W_P}{W_N}$

2.1 MOS Capacitances

- C_{drain} is the intrinsic (self-loading) capacitance of the MOSFET
- C_{gate} is the fanout/extrinsic capacitance
- C_{wire} is the (somewhat negligible) wire capacitance
- **5 capacitor model**

- $C_{gb}, C_{gd}, C_{gs}, C_{sb}, C_{db}$
- we don't really care about C_{sb}

Because of Miller's theorem, we can view C_{gd} as two separate capacitors (one on input, one on output)

There's also overlap capacitance (overlap between gate and drain/source)

- added capacitance from **fringing fields**

Operation Region	C_{gb}	C_{gs}	C_{gd}
Cut-off	$C_{ox}WL$	C_oW	C_oW
Triode	0	$\frac{C_{ox}WL}{2} + C_oW$	$\frac{C_{ox}WL}{2} + C_oW$
Saturation	0	$\frac{2C_{ox}WL}{3} + C_oW$	C_oW

2.1.1 PN-junction Capacitances

- textbook assumes LOCOS (local oxidation of silicon), which is old, and kind of obsolete for post $250\mu m$ processes.
- $C_{diff} = C_{bottom} + C_{sidewall} = C_J * \text{Area} + C_{JSW} * \text{Perimeter} = C_J L_S W + C_{JSW} * (2L_S + W)$
- $C_J = \frac{C_{j0}}{\left(1 + \frac{V_J}{\varphi_B}\right)^m}$ where V_J is the voltage drop across the PN junction, $V_J \leq 0$ for drain-body and source-body connection.

Non-Linear Capacitances

- often times, we will need to use average capacitances.
- $\overline{C} = \frac{1}{V_j - V_i} \int_{V_i}^{V_j} C(V) dV$ where $C(V) = \frac{C_{j0}}{\left(1 + \frac{V}{\varphi_B}\right)^m}$
- we end up with $\overline{C} = K_{eq} C_{j0}$